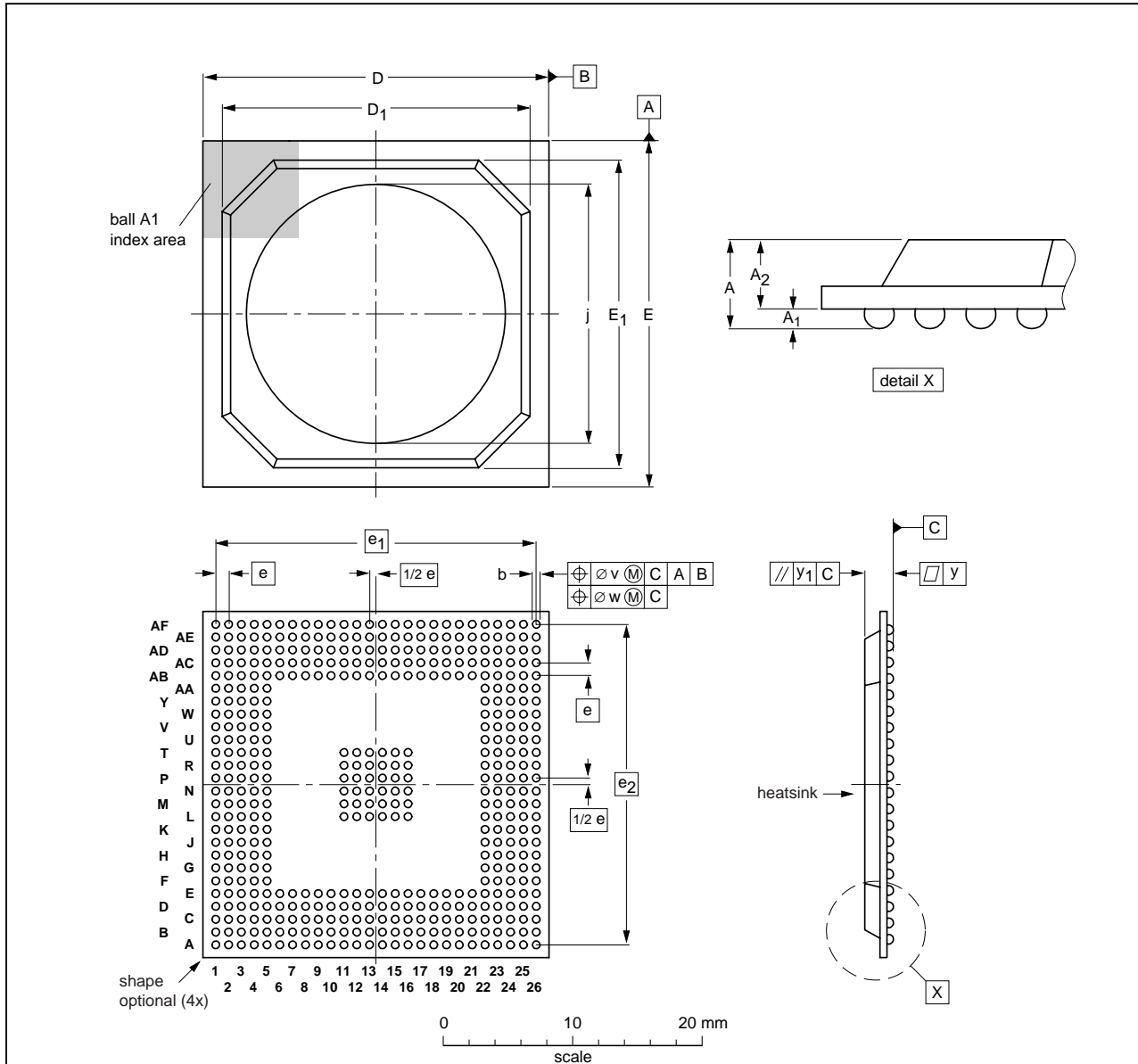


HBGA456: plastic thermal enhanced ball grid array package; 456 balls;
body 27 x 27 x 1.75 mm; heatsink

SOT900-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	b	D	D ₁	E	E ₁	e	e ₁	e ₂	j	v	w	y	y ₁
mm	2.45	0.6 0.4	1.85 1.60	0.7 0.5	27.2 26.8	24.75 23.75	27.2 26.8	24.75 23.75	1	25	25	22 18	0.25	0.1	0.2	0.35

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT900-1	144E	MS-034	---			05-04-11 05-09-02